# **LNJ03004GDD1**

## Surface Mounting Chip LED

3230 Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	860	mW	
Forward current *1	$I_F$	120	mA	
Pulse forward current *2	I <sub>FP</sub>	200	mA	
Junction temperature	Tj	110	°C	
Operating ambient temperature	T <sub>opr</sub>	$T_{\rm opr}$ -30 to +85		
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

### ■ Lighting Color

• White (6500 [Kelvin])

Note) \*1:  $I_F$  is different by radiated factor of evaluation board.

This value is mounted on evaluation board at Rthj-a = 25.0 °C/W.

\*2: The condition of pulse current I<sub>FP</sub> is 55 ms pulse width, 10 % duty.

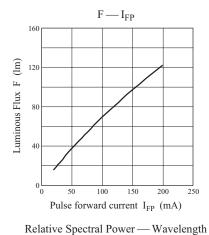
### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

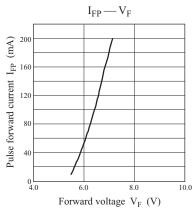
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage *1	V <sub>F</sub>	$I_{FP} = 75 \text{ mA}$	5.7	6.2	6.7	V
Luminous flux *2	F	$I_{FP} = 75 \text{ mA}$	37.0	54.0	80.0	lm
Chromaticity coordinates *3	X	$I_{FP} = 75 \text{ mA}$		0.313		_
	у	$I_{FP} = 75 \text{ mA}$		0.330		_
Color Rendering Index	Ra	$I_{FP} = 75 \text{ mA}$		82		_

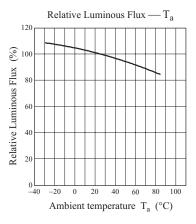
Note) \*1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance ±3%

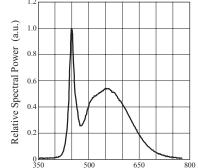
\*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance ±10%

 $*3: \ Complete \ Chromaticity \ coordinates \ measurement \ within \ 0.1 \ seconds. \ Tolerance \ of \ chromaticity \ is \ \pm 0.01 \ seconds.$ 

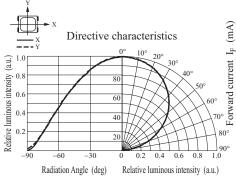


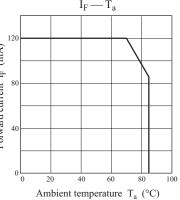




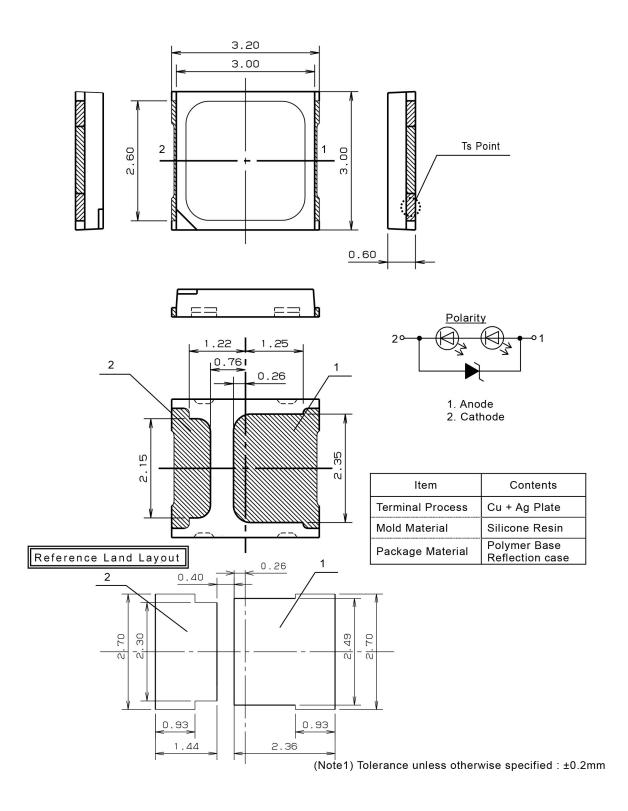


Wavelength (nm)





#### ■ Package (Unit: mm)



Ver. DEK 2

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